

PAM-XIAMEN specializes in GaN-based ultra high brightness blue and green light emitting diodes (LED) and laser diodes (LD). Also we offer GaN Free-standing wafer and GaN Templates(GaN-on-Sapphire).

GaN Wafer

Product Specifications

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GaN on Al2O3-2" epi wafer Specification

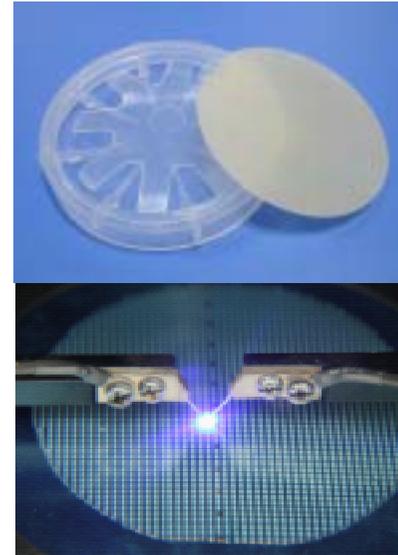
White : 445 ~ 460 nm

Blue : 465 ~ 475 nm

Green : 510 ~ 530 nm

1. Growth Technique - MOCVD
2. Diameter: 50.8mm
3. Substrate material: Patterned Sapphire Substrate(Al2O3)
4. Pattern size: 3X2X1.5μm
5. Structure:

| Structure layers | Thickness(μm) |
|-------------------------|---------------|
| p-GaN | 0.2 |
| p-AlGaIn | 0.03 |
| InGaIn/GaN(active area) | 0.2 |
| n-GaN | 2.5 |
| u- GaN | 2 |
| Al2O3 (Substrate) | 430 |



6. Parameters to make chips:

| Item | Color | Chip Size | Characteristics | Appearance | Application |
|------------|-------|---------------|---|---|---|
| PAM1023A01 | Blue | 10mil x 23mil | Vf = 2.8~3.4V Po = 18~25mW Wd = 450~460nm |  | Lighting LCD backlight Mobile appliances Consumer electronic |
| PAM454501 | Blue | 45mil x 45mil | Vf = 2.8~3.4V Po = 250~300mW Wd = 450~460nm |  | General lighting LCD backlight Outdoor display |

*If you need to know more detail information of Blue LED Chip, please contact with our sales departments



2" GaN Template

| Item | PAM-GaNT-N | PAM-GaNT-SI |
|---------------------|--------------------------------|-------------------------|
| Conduction Type | N-type | Semi-insulating |
| Size | 2"(50mm) dia. | |
| Thickness | 20um,30um | 30um,90um |
| Orientation | C-axis(0001)+/-1 ^o | |
| Resistivity(300K) | <0.05Ω·cm | >1x10 ⁶ Ω·cm |
| Dislocation Density | <1x10 ⁸ cm-2 | |
| Substrate Structure | Thick GaN on Sapphire(0001) | |
| Surface Finish | Double Side Polished,epi-ready | |
| Usable Area | 90 % | |

2"GaN Free-standing Wafer

| Item | PAM-GaN50-N | PAM-GaN50-SI |
|----------------------|---|-------------------------|
| Conduction Type | N-type | Semi-insulating |
| Size | 2"(50mm) dia. | |
| Thickness | 230+/-20um, 280+/-20um | |
| Orientation | C-axis(0001)+/-1 ^o | |
| Resistivity(300K) | <0.05Ω·cm | >1x10 ⁶ Ω·cm |
| Dislocation Density | <5x10 ⁶ cm-2 | |
| Marco Defect Density | <5cm-2 | |
| Surface Finish | Double Side Polished,RMS<2nm,N-Face RMS<1μm,epi-ready | |
| Usable Area | 90 % | |



10mm*10.5mm,GaN Free-standing Wafer

| Item | PAM-GaN50-N | PAM-GaN50-SI |
|----------------------|---|-------------------------|
| Conduction Type | N-type | Semi-insulating |
| Size | 10mmx10.5mm | |
| Thickness | 230+/-20um, 280+/-20um | |
| Orientation | C-axis(0001)+/-1 ⁰ | |
| Resistivity(300K) | <0.05Ω·cm | >1x10 ⁶ Ω·cm |
| Dislocation Density | <5x10 ⁶ cm-2 | |
| Marco Defect Density | <5cm-2 or 5-10cm-2 | <5cm-2 |
| Surface Finish | Double Side Polished,RMS<2nm,N-Face RMS<1μm,epi-ready | |
| Usable Area | 90 % | |